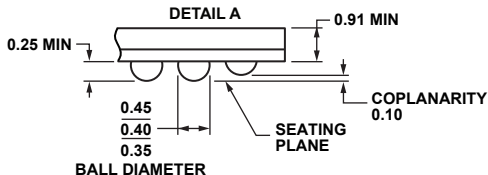
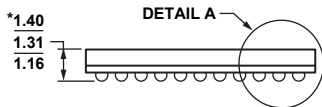
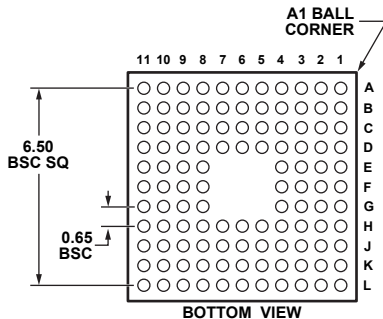
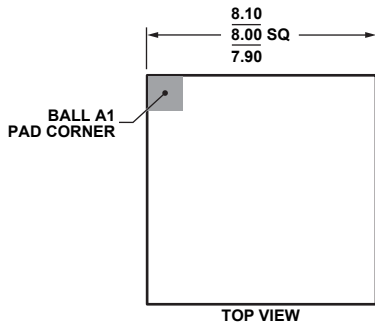


112-Ball Chip Scale Package Ball Grid Array [CSP_BGA] (BC-112-1)

Dimensions shown in millimeters



*COMPLIANT TO JEDEC STANDARDS MO-225
WITH THE EXCEPTION TO PACKAGE HEIGHT.